

Abstract

A method of packaging electronic components includes the steps
of forming a plurality of cavities (6) in a package substrate
5 (2; 20), mounting the electronic components (8) in the
cavities (6), sealing the cavities (6) with a cover substrate
or a cover layer (4) and separating the components (8)
packaged in this way. This permits inexpensive simultaneous
10 production of a plurality of component packages. In one
variant of the method, the components are arranged on a
component carrier layer (16), the components being mounted in
the cavities (6) by joining the package substrate (2; 20) and
the component carrier layer (16).

18 Figures 1 and 2

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